



PRODUCT DESCRIPTION

Laird's Tflex™ HD90000 is the latest product in our High Deflection series. Tflex™ HD90000 combines 7.5 W/mK thermal conductivity with superior pressure versus deflection characteristics. The combination will allow minimal stress on components while also yielding low thermal resistance. As a result, less mechanical and thermal stresses will be experienced within your device.

Tflex™ HD90000 is available in thickness from 0.020" (500 µm) to 0.200" (5000 µm). Laird can provide material to meet your production needs in any region through our local production facilities. Please contact your local Laird sales or field engineering contact for samples or questions.

FEATURES AND BENEFITS

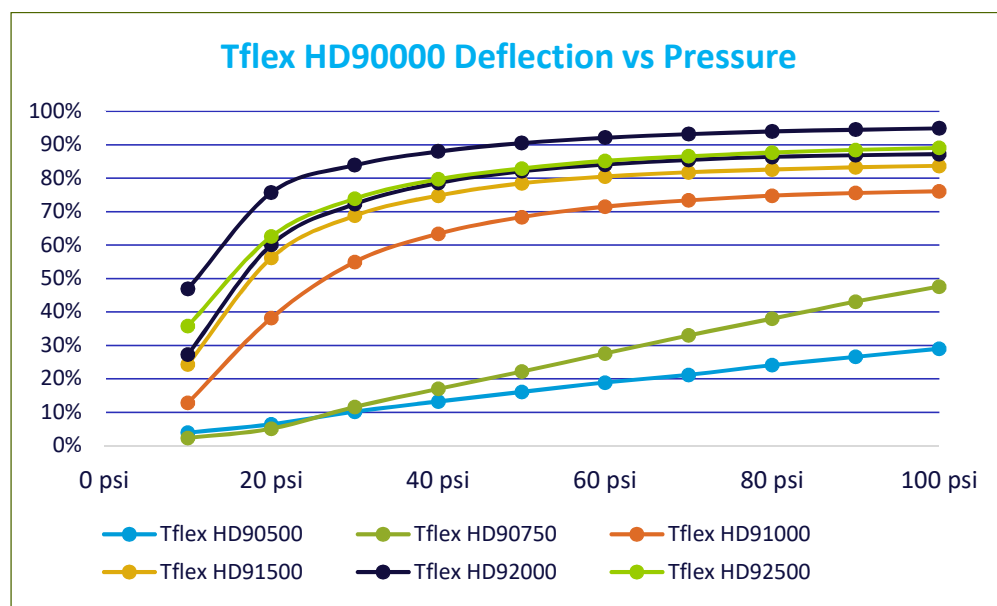
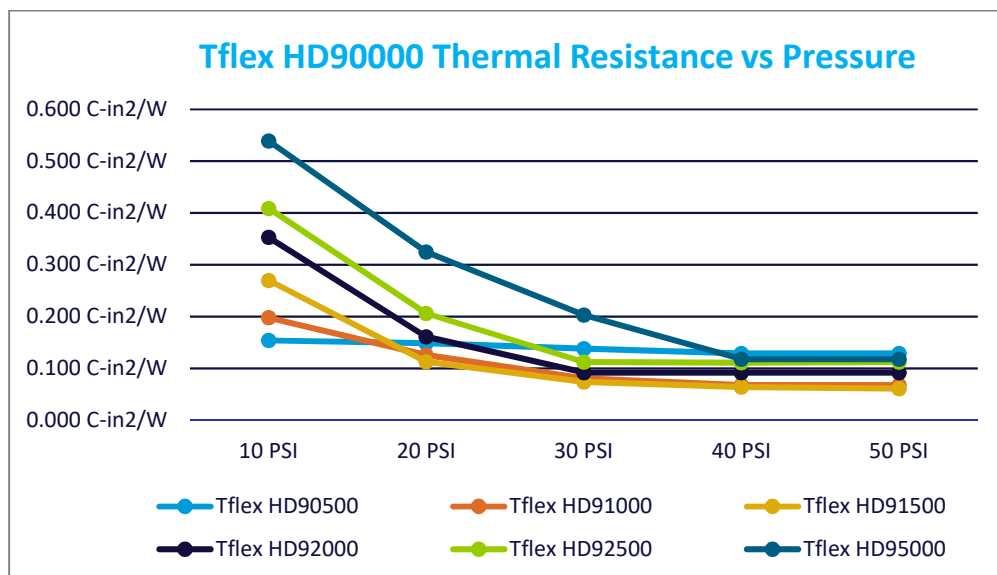
- 7.5 W/mK thermal conductivity
- Low pressure versus deflection
- Excellent surface wetting for low contact resistance
- Minimizes board and component stress
- Low Outgassing
- Low D3-D20 (< 20ppm)
- Large tolerance applications
- Environmentally friendly solution that meets regulatory requirements including RoHS and REACH

SPECIFICATIONS

TYPICAL PROPERTIES	VALUE	TEST METHOD
Construction & Composition	Ceramic filled silicone sheet	N/A
Color	Grey	Visual
Thickness Range	0.020" (500 µm) - 0.200" (5000 µm)	N/A
Thermal Conductivity (W/mK)	7.5	Hot Disk
Density (g/cc)	3.5	Helium Pycnometer
Hardness (Shore 00)	500 and 750 µm: 45 1000 µm and up: 32	ASTM D2240
Outgassing TML (weight %)	0.17	ASTM E595
Outgassing CVCN (weight %)	0.01	ASTM E595
Temperature Range	-50°C to 125°C	Laird Test Method
Rth at 40 mils, 10 psi, 50° C	0.198°C-in2/W	ASTM D5470
Dielectric Constant at 1 MHz	8.14	ASTM D150
UL Flammability Rating	V-0	UL 94
Volume Resistivity	8.73×10^{13} ohm-cm	ASTM D257

Americas: +1.866.928.8181
Europe: +49.(0).8031.2460.0
Asia: +86.755.2714.1166

www.lairdtech.com



AVAILABILITY

STANDARD THICKNESSES

- 0.020" (500 µm) up to 0.200" (5000 µm) thick material available in 250 µm increments
- Available in standard sheet sizes of 18" x 18" (1000 µm and up only) and 9" x 9" or custom die cut parts.

PART NUMBER SYSTEM

Tflex™ indicates Laird elastomeric thermal gap filler product line. HD90000 indicates Tflex™ HD90000 product line with thickness in microns

EXAMPLES:

- Tflex™ HD91000= 1000 µm (0.040") thick Tflex™ HD90000 material
- Tflex™ HD95000= 5000 µm (0.200") thick Tflex™ HD90000 material

A17807-00 Tflex™ HD90000 DS 06062019

Any information furnished by Laird Technologies, Inc. and its agents is believed to be accurate and reliable. All specifications are subject to change without notice. Responsibility for the use and application of Laird Technologies materials rests with the end user. Laird Technologies makes no warranties as to the fitness, merchantability, suitability or non-infringement of any Laird Technologies materials or products for any specific or general uses. Laird Technologies shall not be liable for incidental or consequential damages of any kind. All Laird Technologies products are sold pursuant to the Laird Technologies' Terms and Conditions of sale in effect from time to time, a copy of which will be furnished upon request. © Copyright 2013 Laird Technologies, Inc. All Rights Reserved. Laird, Laird Technologies, the Laird Technologies Logo, and other marks are trademarks or registered trademarks of Laird Technologies, Inc. or an affiliate company thereof. Other product or service names may be the property of third parties. Nothing herein provides a license under any Laird Technologies or any third party intellectual property rights.



Tflex™ HD90000 Series

Thermal Gap Filler

A17807-00 Tflex™ HD90000 DS 06062019

Any information furnished by Laird Technologies, Inc. and its agents is believed to be accurate and reliable. All specifications are subject to change without notice. Responsibility for the use and application of Laird Technologies materials rests with the end user. Laird Technologies makes no warranties as to the fitness, merchantability, suitability or non-infringement of any Laird Technologies materials or products for any specific or general uses. Laird Technologies shall not be liable for incidental or consequential damages of any kind. All Laird Technologies products are sold pursuant to the Laird Technologies' Terms and Conditions of sale in effect from time to time, a copy of which will be furnished upon request. © Copyright 2013 Laird Technologies, Inc. All Rights Reserved. Laird, Laird Technologies, the Laird Technologies Logo, and other marks are trademarks or registered trademarks of Laird Technologies, Inc. or an affiliate company thereof. Other product or service names may be the property of third parties. Nothing herein provides a license under any Laird Technologies or any third party intellectual property rights.